

MOSFET

OptiMOS[™]-T2 Power Transistor, 60 V

Features

- Dual N-channel, Logic level
 Fast switching MOSFETs for SMPS
 Optimized technology for Synchronous Rectification
 Pb-free plating; RoHS compliant
 100% Avalanche tested

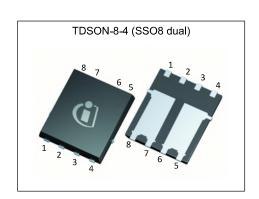
- · Superior Thermal Resistance
- · Halogen-free according to IEC61249-2-21

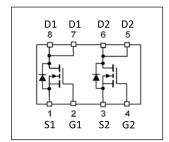
Product validation

Fully qualified according to JEDEC for Industrial Applications

Table 1 **Key Performance Parameters**

Parameter	Value	Unit
V _{DS}	60	V
R _{DS(on),max}	11.2	mΩ
I _D	57	A











Type / Ordering Code	Package	Marking	Related Links
BSC112N06LD	PG-TDSON-8-4	112N06LD	-

OptiMOSTM-T2 Power Transistor, 60 V BSC112N06LD



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Maximum ratings

at T_A=25 °C, unless otherwise specified, one transistor active

Table 2 **Maximum ratings**

Davamatav	C: mala al	Values			11!4	N 4 / T 4 O 199
Parameter	Symbol	Min.	Тур.	Max.	Unit	Note / Test Condition
Continuous drain current ¹⁾	I _D	-	-	57	Α	V _{GS} =10 V, T _C =25 °C
Pulsed drain current ²⁾	I _{D,pulse}	-	-	228	Α	T _A =25 °C
Avalanche energy, single pulse ³⁾	E _{AS}	-	-	80	mJ	$I_{\rm D}$ =10 A, $R_{\rm GS}$ =25 Ω
Gate source voltage	V _{GS}	-16	-	16	V	-
Power dissipation	P _{tot}	-	-	65	W	T _C =25 °C
Operating and storage temperature	$T_{\rm j},~T_{\rm stg}$	-55	-	175	°C	IEC climatic category; DIN IEC 68-1: 55/175/56

2 Thermal characteristics

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
	Symbol	Min.	Тур.	Max.	Oilit	Note / Test Condition
Thermal resistance, junction - case, bottom	R _{thJC}	_	-	2.3	°C/W	-
Device on PCB, 6 cm² cooling area ⁴⁾	R_{thJA}	-	-	60	°C/W	-
Device on PCB, minimal footprint ⁵⁾	R _{thJA}	_	-	100	°C/W	-

¹⁾ Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature as specified. For other case temperatures please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

2) See Diagram 3 for more detailed information

³⁾ See Diagram 13 for more detailed information
⁴⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

⁵⁾ device mounted on a minimum pad (one layer, 70 µm thick)

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3 Electrical characteristics at T_j =25 °C, unless otherwise specified

Table 4 **Static characteristics**

Davamatav	Symbol	Values			11	Nata / Tast Candition
Parameter	Symbol	Min.	Тур.	Max.	Unit	Note / Test Condition
Drain-source breakdown voltage	$V_{(BR)DSS}$	60	-	-	V	V _{GS} =0 V, I _D =1 mA
Gate threshold voltage	$V_{\rm GS(th)}$	1.2	1.7	2.2	V	$V_{\rm DS}=V_{\rm GS},\ I_{\rm D}=28\ \mu {\rm A}$
Zero gate voltage drain current	$I_{ m DSS}$	-	0.1 5.0	1.0 100	μA	V _{DS} =60 V, V _{GS} =0 V, T _j =25 °C V _{DS} =60 V, V _{GS} =0 V, T _j =125 °C
Gate-source leakage current	I _{GSS}	-	-	100	nA	V _{GS} =16 V, V _{DS} =0 V
Drain-source on-state resistance	R _{DS(on)}	-	9.5 12.5	11.2 15.8	mΩ	V _{GS} =10 V, I _D =17 A V _{GS} =4.5 V, I _D =10 A

Table 5 **Dynamic characteristics**

Devementar	Symph al	Values			11:4	Nata / Tank Oam distant
Parameter	Symbol	Min.	Тур.	Max.	Unit	Note / Test Condition
Input capacitance ¹⁾	Ciss	-	3090	4020	pF	V _{GS} =0 V, V _{DS} =30 V, f=1 MHz
Output capacitance ¹⁾	Coss	-	590	770	pF	V _{GS} =0 V, V _{DS} =30 V, f=1 MHz
Reverse transfer capacitance ¹⁾	C _{rss}	-	28	56	pF	V _{GS} =0 V, V _{DS} =30 V, f=1 MHz
Turn-on delay time	$t_{\sf d(on)}$	-	11	_	ns	$V_{\rm DD}$ =30 V, $V_{\rm GS}$ =10 V, $I_{\rm D}$ =20 A, $R_{\rm G,ext}$ =11 Ω
Rise time	t _r	-	3	-	ns	V_{DD} =30 V, V_{GS} =10 V, I_{D} =20 A, $R_{\text{G,ext}}$ =11 Ω
Turn-off delay time	$t_{ m d(off)}$	-	51	_	ns	$V_{\rm DD}$ =30 V, $V_{\rm GS}$ =10 V, $I_{\rm D}$ =20 A, $R_{\rm G,ext}$ =11 Ω
Fall time	t _f	-	7	_	ns	$V_{\rm DD}$ =30 V, $V_{\rm GS}$ =10 V, $I_{\rm D}$ =20 A, $R_{\rm G,ext}$ =11 Ω

Table 6 Gate charge characteristics²⁾

Parameter	O and a d	Values				
	Symbol	Min.	Тур.	Max.	Unit	Note / Test Condition
Gate to source charge	Q _{gs}	-	10	13	nC	V _{DD} =30 V, I _D =20 A, V _{GS} =0 to 10 V
Gate to drain charge	Q_{gd}	-	3.4	6.7	nC	V_{DD} =30 V, I_{D} =20 A, V_{GS} =0 to 10 V
Gate charge total	Qg	-	41	55	nC	$V_{\rm DD}$ =30 V, $I_{\rm D}$ =20 A, $V_{\rm GS}$ =0 to 10 V
Gate plateau voltage	V _{plateau}	-	3.2	-	V	$V_{\rm DD}$ =30 V, $I_{\rm D}$ =20 A, $V_{\rm GS}$ =0 to 10 V

¹⁾ Defined by design. Not subject to production test.
²⁾ See "Gate charge waveforms" for parameter definition. Defined by design, not subject to production test

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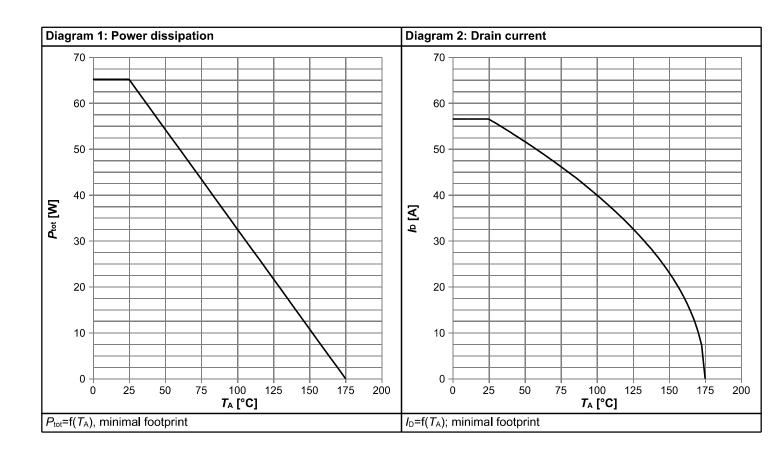


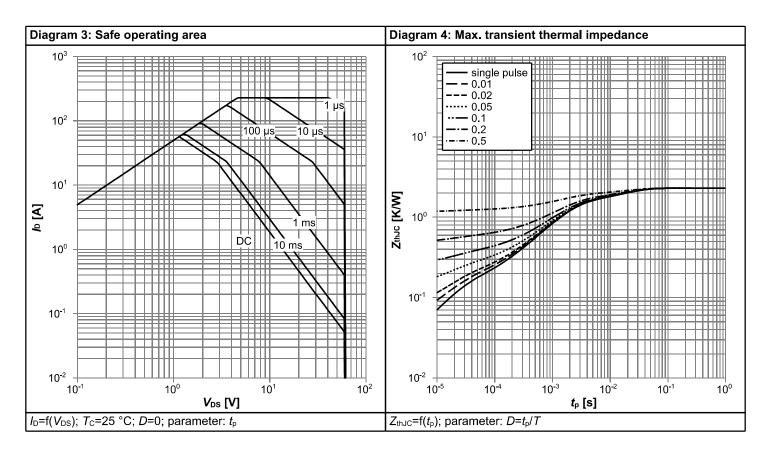
Table 7 Reverse diode

Parameter	Symbol		Values			Nata / Tank Canadition
	Symbol	Min.	Тур.	Max.	Unit	Note / Test Condition
Diode continuous forward current	I _S	-	-	38	Α	T _C =25 °C
Diode pulse current	I _{S,pulse}	-	-	228	Α	T _C =25 °C
Diode forward voltage	V _{SD}	-	0.88	1.1	V	V _{GS} =0 V, I _F =17 A, T _j =25 °C
Reverse recovery time	t _{rr}	-	35	-	ns	V _R =30 V, I _F =9 A, d <i>i</i> _F /d <i>t</i> =100 A/μs
Reverse recovery charge	Q _{rr}	_	35	-	nC	V _R =30 V, I _F =9 A, d <i>i</i> _F /d <i>t</i> =100 A/μs

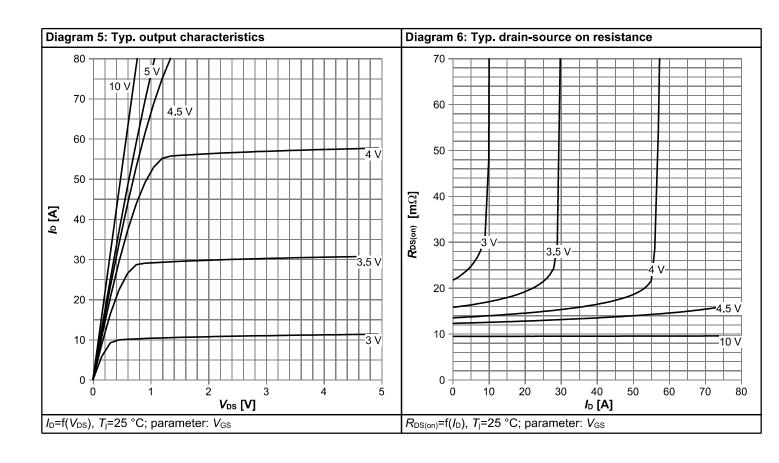


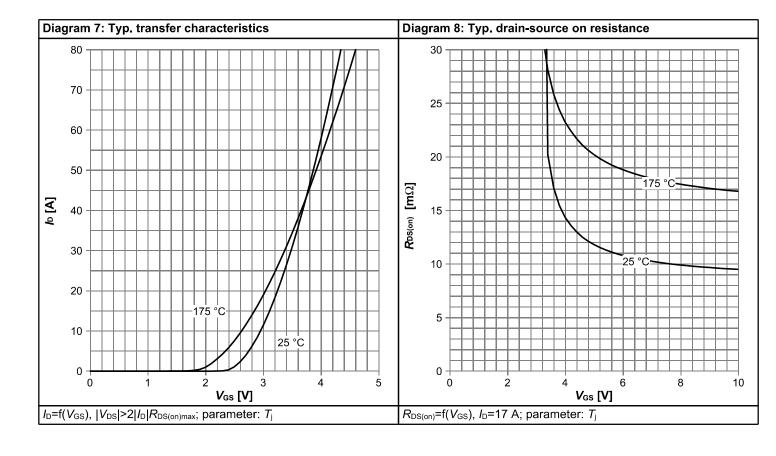
4 Electrical characteristics diagrams



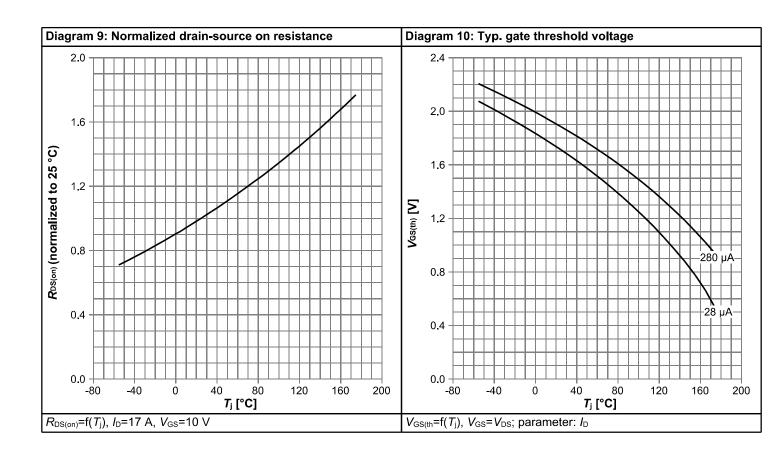


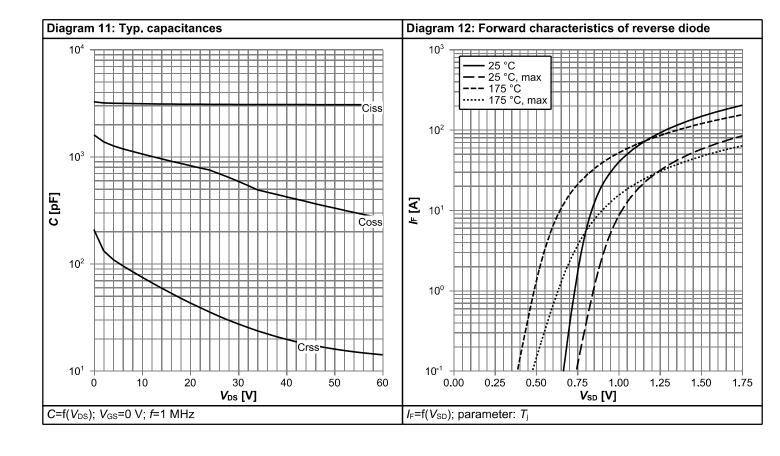




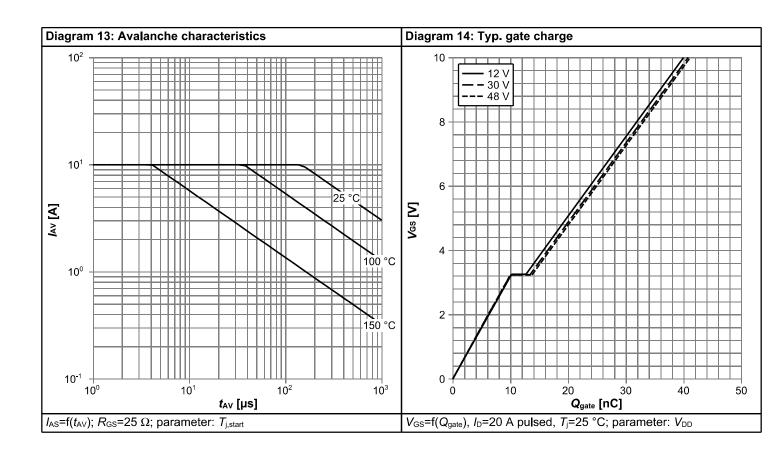


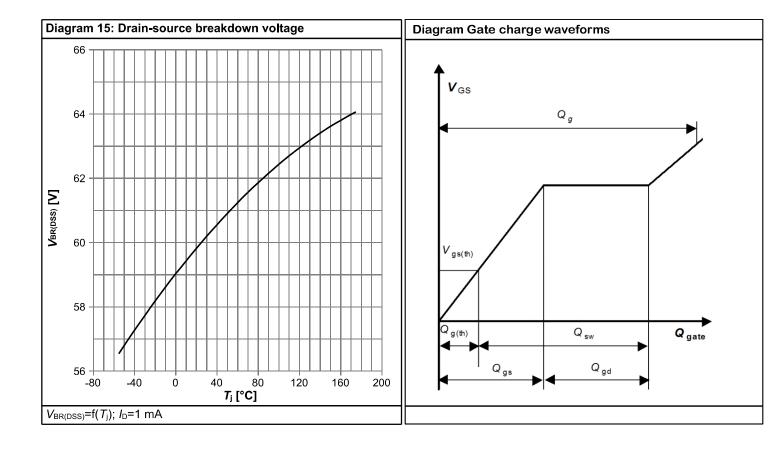






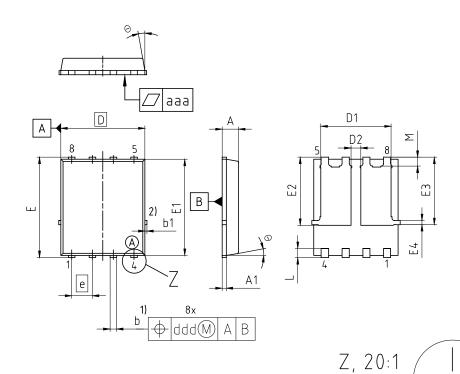








5 Package Outlines



1) EXCLUDE MOLD FLASH

2) REMOVAL ON MOLD GATE, INTRUSION 0.1 mm PROTRUSION 0.1 mm

ALL METAL SURFACES ARE PLATED EXCEPT AREA OF CUT

DIMENSIONS	MILLIM	ETERS				
DIMENSIONS	MIN.	MAX.				
Α	0.90	1.10				
A1	0.15	0.35				
b	0.34	0.54				
b1	0.02	0.22				
D	4.95	5.35				
D1	4.20	4.40				
D2	0.50	0.70				
E	5.95	6.35				
E1	5.70	6.10				
E2	4.075	4.275				
E3	4.035	4.235				
E4	0.15	0.35				
е	1.27					
L	0.45	0.65				
М	0.45	0.65				
Θ	8.5° 11.5°					
aaa	0.05					
ddd	0.	10				

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0 1 2 3 4mm Luuluuluuluul					
EUROPEAN PROJECTION					
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MOLD FLASH ALONG

SIDE OF LEADS

Figure 1 Outline PG-TDSON-8-4, dimensions in mm

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Revision History

BSC112N06LD

Revision: 2021-06-28, Rev. 2.1

Previous Revision

	The visual restriction						
Revision	Revision Date Subjects (major changes since last revision)						
2.0	2018-12-11	Release of final version					
2.1	2021-06-28	Update current rating, footnotes and Id Diagram 9					

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